#### QUADRUPLE 2-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS

APRIL 1985 - REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

### description

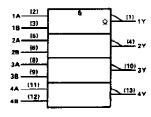
These devices contain four independent 2-input NAND gates. The open-collector outputs require pull-up resistors to perform correctly. They may be connected to other open-collector outputs to implement active-low wired-OR or active-high wired-AND functions. Open-collector devices are often used to generate higher VOH levels.

The SN5401 and SN54LS01 are characterized for operation over the full military temperature range of  $-55\,^{\circ}\text{C}$  to  $125\,^{\circ}\text{C}$ . The SN7401 and SN74LS01 are characterized for operation from  $0\,^{\circ}\text{C}$  to  $70\,^{\circ}\text{C}$ .

#### **FUNCTION TABLE (each gate)**

INP	UTS	OUTPUT
Α	В	Υ
Н	н	L
L	X	[ н
×	L	н

#### logic symbol†



<sup>&</sup>lt;sup>†</sup>This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

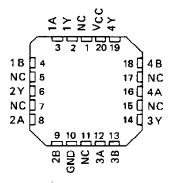
SN5401 . . . J PACKAGE SN54LS01 . . . J OR W PACKAGE SN7401 . . . N PACKAGE SN74LS01 . . . D OR N PACKAGE (TOP VIEW)

1Y	Пı	U14 Vcc
1A	$\square$ 2	13 4 Y
1 B	□3	12 🗆 4 B
2Y	□4	11 AA
2A	<b>Д</b> 5	10 <b>]</b> 3 Y
2B	<b>□</b> 6	9∏ 3B
GND	ď۶	8 <b>∐ 3A</b>

# SN5401 . . , W PACKAGE (TOP VIEW)

	_	
1 A	ďι	U 14] 4 Y
1 B	$\square^2$	13 🗀 4 B
1 Y	Дз	12 AA
V c c	□₄	סאם [ויו GND
2 Y	□5	10 <b>Д 3 В</b>
2A	<b>□</b> 6	9∐3A
2 B	口7	8 🗖 3 Ƴ

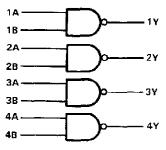
# SN54LS01 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

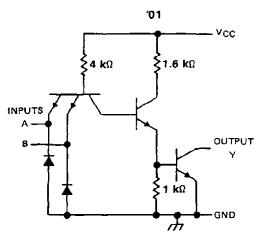
### QUADRUPLE 2-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS

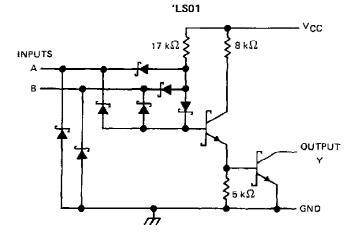
### logic diagram (positive logic)



positive logic;  $Y = \overline{A \cdot B}$  or  $Y = \overline{A} + \overline{B}$ 

### schematics (each gate)





Resistor values shown are nominal.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1): '0	, 'LS01	7 V
'LSO1		7 V
Off-state output voltage		7 V
Operating free-air temperature range:	SN54'	5°C to 125°C
	5N74'	0°C to 70°C
Storage temperature range		5°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminals.

# SN5401, SN7401 QUADRUPLE 2-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS

#### recommended operating conditions

		SN5401			SN7401			
	MIN	NOM	MAX	MIN	NOM	мах	UNIT	
V <sub>CC</sub> Supply voltage	4.5	5	5,5	4.75	5	5.25	٧	
V <sub>IH</sub> High-level input voltage	2			2			٧	
VIL Low-level input voltage			8.0			0.8	V	
VOH High-level output voltage			5.5			5.5	V	
IOL Low-level output current			16			16	mA	
TA Operating free-air temperature	- 55		125	0	·	70	°C	

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST CONDITIONS <sup>†</sup>	SN5401	SN7401	
PARAMETER	TEST CONDITIONS.	MIN TYP# MAX	MIN TYP‡ MAX	UNIT
Vik	V <sub>CC</sub> = MIN,   <sub>I</sub> = -12 mA	- 1.5	-1.5	V
	VCC = MIN, VIL = 0.8 V, VOH = 5.5 V		0.25	- ^
Іон	VCC = MIN, VIL = 0.7 V, VOH = 5.5 V	0.25		mA
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 16 mA	0.2 0.4	0.2 0.4	V
4	VCC = MAX, VI = 5.5 V	1	1	mA
lн	$V_{CC} = MAX$ , $V_{I} = 2.4 \text{ V}$	40	40	μΑ
IIL	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V	-1.6	-1.6	mA
<b>І</b> ссн	$V_{CC} = MAX, V_I = 0$	4 8	4 8	mA
<sup>I</sup> CCL	$V_{CC} = MAX$ , $V_{\parallel} = 4.5 \text{ V}$	12 22	12 22	mA

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

### switching characteristics, VCC = 5 V, $T_A = 25^{\circ}C$ (see note 2)

PARAMETER	FROM (INPUT)	<b>T</b> O (OUTPUT)	TEST COND	MIN TY	P MAX	TINU	
<sup>₹</sup> PLH	A or B	V	RL=4kΩ,	C <sub>L</sub> = 15 pF		35 55	ns
<sup>t</sup> PHL		,	R <sub>L</sub> = 400 Ω,	C <sub>L</sub> = 15 pF		8 15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

 $<sup>^{\</sup>ddagger}$ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25 °C.

## SN54LS01, SN74LS01 QUADRUPLE 2-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS

#### recommended operating conditions

		SN54LS01			SN74LS01			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
V <sub>CC</sub> Supply voltage	4,5	5	5.5	4.75	5	5.25	٧	
V <sub>IH</sub> High-level input voltage	2			2			V	
VIL Low-level input voltage		-	0.7			0.8	V	
VOH High-level output voltage			5.5			5.5	V	
IOL Low-level output current			4			8	mА	
TA Operating free-air temperature	- 55		125	0		70	°c	

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

040445750	ţ									
PARAMETER	į	TEST CONDI	TIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
Vik	V <sub>CC</sub> - MIN,	I <sub>I</sub> = ~ 18 mA	I <sub>I</sub> = ~ 18 mA			- 1.5				V
•он	V <sub>CC</sub> = MIN,	VIL = MAX,	V <sub>OH</sub> = 5.5 ∨			0.1			0.1	mA
14	VCC = MIN,	V <sub>IH</sub> = 2 V,	IOL = 4 mA		0.25	0.4		0.25	0.4	V
V <sub>OL</sub>	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	IOL - 8 mA					0.35	0.5	
41	VCC = MAX.	V <sub>1</sub> = 7 V				0.1			0.1	mA
ЙH	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.7 V			_	20			20	μА
412	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V	· · · · · · · · · · · · · · · · · · ·			- 0.4			- 0.4	mA
1ссн	VCC = MAX,	V <sub>I</sub> = 0	<del></del>		0.8	1.6		0.8	1.6	mΑ
1CCΓ	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 4.5 V			2.4	4.4		2.4	4.4	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

# switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST COM	MłN	TYP	MAX	UNIT	
tPLH	A or B	·	R <sub>1</sub> = 2 kΩ,	C <sub>L</sub> = 15 pF		17	32	ns
<sup>‡</sup> PHL	70.0		11[ - 2 K32,	C[ 13 pi		15	28	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

<sup>‡</sup> All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25°C.





15-Apr-2017

#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN5401J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN5401J	Samples
SN54LS01J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS01J	Samples
SN54LS01J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS01J	Samples
SNJ5401J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ5401J	Samples
SNJ5401J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ5401J	Samples
SNJ5401W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ5401W	Samples
SNJ5401W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ5401W	Samples
SNJ54LS01J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS01J	Samples
SNJ54LS01J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS01J	Samples
SNJ54LS01W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS01W	Samples
SNJ54LS01W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS01W	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



### PACKAGE OPTION ADDENDUM

15-Apr-2017

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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# W (R-GDFP-F14)

# CERAMIC DUAL FLATPACK



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



#### NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



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